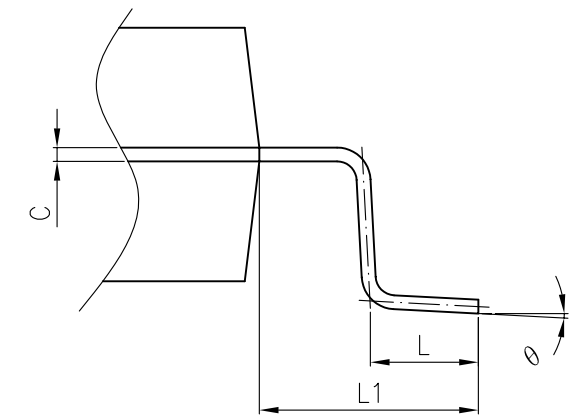
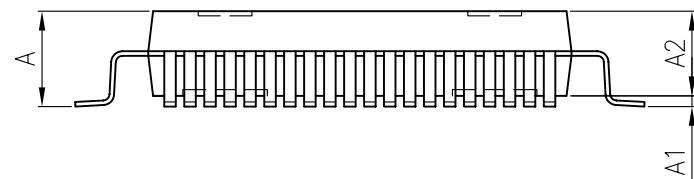
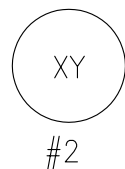


BOTTOM E-PIN INDENT #2  $\phi$ 0.110  
NOTE 6



NOTE :

1. CONTROLLING DIMENSION : INCH
2. LEAD FRAME MATERIAL : C7025
3. AFTER SOLDER PLATING LEAD THICKNESS WILL BE 0.008" MAX.
4. PACKAGE DIMENSION EXCLUSIVE MOLDING FLASH.
5. RESIN PROTRUSION BETWEEN LEAD TO LEAD SHALL NOT EXCEED 0.006" PER SIDE.
6. BOTTOM E-PIN INDENTS ARE MARKED AS BELOW:



X : A ~ M  
Y : 1 ~ 6  
NO : DENOTE MOLD SET NUMBER

SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
$\triangle$ A	2.75	3.05	3.40	0.108	0.120	0.134
$\triangle$ A1	0.25	0.35	0.50	0.010	0.014	0.020
$\triangle$ A2	2.50	2.70	2.90	0.098	0.106	0.114
$\triangle$ b	0.22	—	0.40	0.009	—	0.016
$\triangle$ C	0.11	0.15	0.23	0.004	0.006	0.009
$\triangle$ E	16.94	17.20	17.45	0.667	0.677	0.687
$\triangle$ E1	13.89	14.00	14.10	0.547	0.551	0.555
$\triangle$ D	22.96	23.20	23.44	0.904	0.913	0.923
$\triangle$ D1	19.89	20.00	20.09	0.783	0.787	0.791
$\triangle$ e	—	0.65	—	—	0.0256	—
$\triangle$ L	0.73	0.88	1.03	0.029	0.035	0.041
$\triangle$ L1	—	1.60	—	—	0.063	—
$\theta$	0°	—	7°	0°	—	7°
y	0.00	—	0.076	0.000	—	0.003

CUSTOMER :	
APPROVED BY	DATE
DRAW BY: <i>Kelly Ho</i>	10/19/06
CHECK BY: <i>Jian Jong Lai</i>	10/19/06
APPROVAL: <i>Parker Chen</i>	10/19/06
APPROVAL: <i>Andy Yang</i>	10/20/06

LINGSEN 5-1 NAN 2ND ROAD T.E.P.Z PRECISION IND, LTD TAICHUNG, TAIWAN. R. O. C	
TITLE : 100L QFP PACKAGE OUTLINE DRAWING(14x20 mm) FOOTPRINT: 3.2mm	
DWG. NO. PO-QFP-002	REV. 1
UNIT : INCH	SCALE : 4/1
SHEET 1 OF 1	